

1. FEATURES

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Low forward voltage drop



2. MECHANICAL DATA

- Package: DO-214AA (SMB)
- Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- Terminals: Tin plated leads, solderable per J-STD-002
- Polarity: As marked

3. MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$)

PARAMETER		SYMBOL	GS2A	GS2B	GS2D	GS2G	GS2J	GS2K	GS2M	GS2Q	GS2V	UNIT
Maximum repetitive peak reverse voltage		V _{RRM}	50	100	200	400	600	800	1000	1200	1400	V
Maximum RMS voltage		V _{RMS}	35	70	140	280	420	560	700	840	980	V
Maximum DC blocking voltage		V _{DC}	50	100	200	400	600	800	1000	1200	1400	V
Maximum average forward rectified current		I _{F(AV)}	2									A
Surge(non-repetitive)forward current@60Hz Half-sine wave,1 cycle,Ta=25°C		I _{FSM}	50									A
Typical Junction capacitance@V _r =4.0V,1MHZ		C _J	30									pF
Storage temperature		T _{STG}	-55~+150									°C
Junction temperature		T _J	-55~+150									°C
Typical Thermal Resistance		R _{θJ-A}	53									°C/W
		R _{θJ-L}	16									°C/W
Maximum forward voltage @I _F =2A ^{Note1}		V _F	1.15									V
Maximum reverse current @rated V _R ^{Note2}	T _J =25°C	I _R	1									uA
	T _J =125°C		125									
Typical reverse recovery time @I _F =0.5A,I _R =1.0A,I _{RR} =0.25A		t _{rr}	1.5									uS

Note 1: Pulse test with $PW=0.3\text{mS}$

Note 2: Pulse test with $PW=30\text{mS}$



4. CHARACTERISTICS (typical)

Fig.1: Forward Current Derating Curve

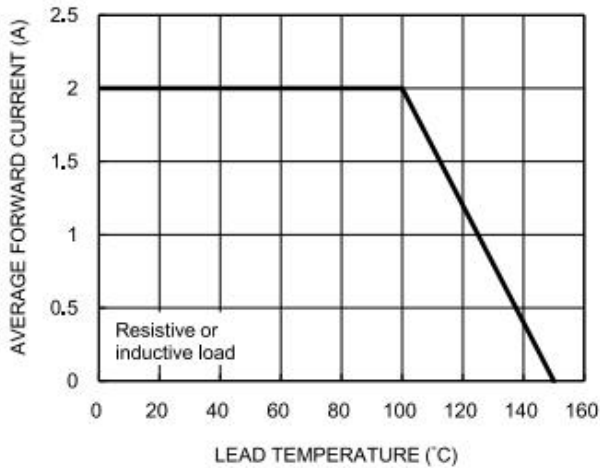


Fig.2: Typical Junction Capacitance

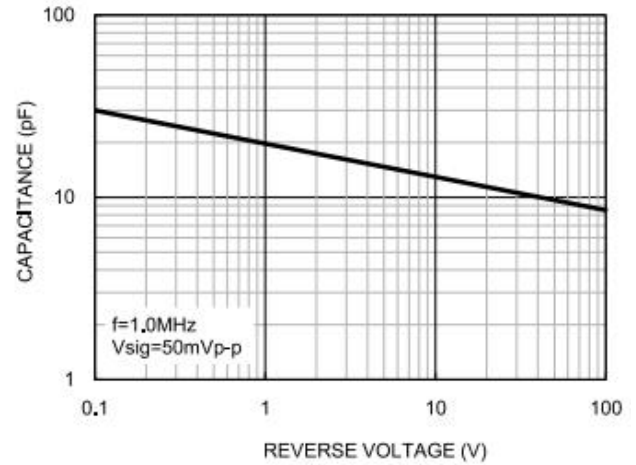


Fig.3: Typical Reverse Characteristics

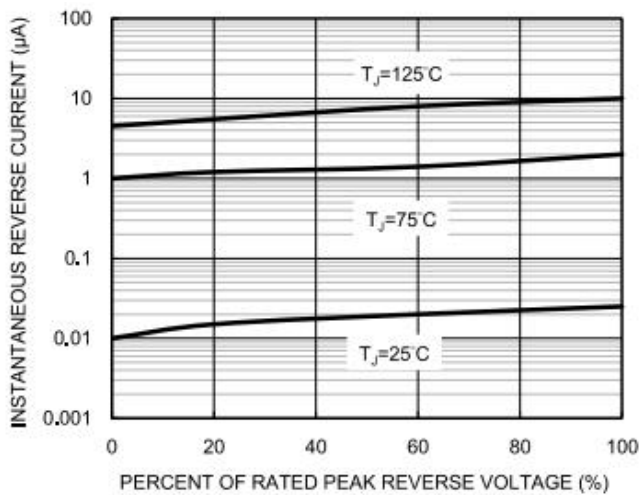
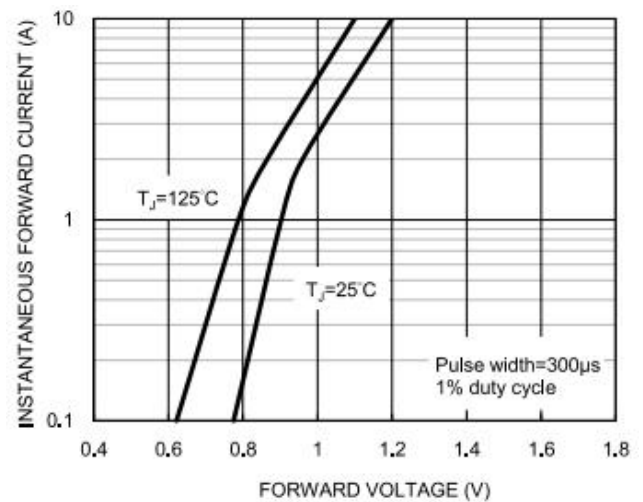


Fig.4: Typical Forward Characteristics



5. SMB(DO-214AA) PACKAGE DIMENSIONS

DIM	MILLIMETERS		INCHES	
	Min.	Max.	Min.	Max.
A	1.96	2.20	0.077	0.087
B	4.35	4.85	0.171	0.191
C	3.30	3.94	0.130	0.155
D	2.20	2.50	0.087	0.098
E	0.76	1.52	0.030	0.060
F	0.02	0.20	0.001	0.008
G	5.08	5.59	0.200	0.220
H	0.15	0.30	0.006	0.012

6. RECOMMENDED PAD LAYOUT DIMENSIONS

DIM	MILLIMETERS		INCHES	
	Min.	Max.	Min.	Max.
A	2.20	-	0.087	-
B	1.45	-	0.057	-
C	-	2.55	-	0.100
D	1.45	-	0.057	-
E	5.60 REF		0.220 REF	

7. ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
GS2A-GS2V	DO-214AA(SMB)	3000PCS	13"



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